

INTERFLUX [®] Electronics

IF 8300



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No-clean, halide free and colophony free gel flux

Description

Interflux[®] **IF 8300** is a no-clean, halide free and colophony free gel flux with minimal residues after soldering.

The gel flux is available in different viscosities for different applications.

It can be applied by printing, dispensing, dipping or by brush.

IF 8300 is typically used for rework and repair applications. Other fields of use can be reflow, hand and robot soldering applications where a wide process window in combination with low residue formation after soldering are required.

The gel flux is compatible with both lead-free and SnPb alloys and enables good wetting on virtually all surface finishes.

Physical and chemical properties

	IF 8300	IF 8300-4	IF 8300-6
Consistency	viscous, tacky		
Colour	yellow		
Odour	sweet, mild		
Halide content	none		
pH (5% aq.sol)	3		
IPC/ EN	RE LO		
Solubility in water	insoluble		
Auto-ignition point	> 370 °C		
Flash point	158 °C	144°C	137°C
Specific gravity	1,032 g/ml	1,020 g/ml	1,013 g/ml
Viscosity at 20 °C	± 210.000 cPs	± 70.000 cPs	± 25.000 cPs

The residues are minimal and transparent and do not require cleaning.

IF 8300 is absolutely halide free providing optimal reliability after soldering.





Products pictured may differ from the product delivered





Click for Interflux' ecological profile

Key properties

- Absolutely halogen free
- Colophony free
- Wide process window
- Enables good wetting NiAu, OSP, I-Sn, AgPd,....
- Minimal residue

Technical Data IF 8300 Ver: 5.0 21-02-24





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Soldering profile recommendations for IF 8300

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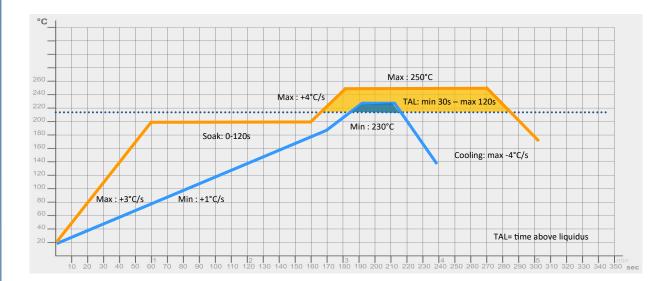
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Regardless of the used soldering technique, it is always important to know the physical limitations of the components and base materials to be soldered and to adapt the soldering profile to these limitations.

Hand soldering : For Sn(Ag)Cu alloys, the advised working temperature is between 320°C and 390°C. For SnPb(Ag) alloys, this is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated. Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and solder pad. The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible. Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire, the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip.

Reflow soldering: The used soldering profile will mainly be determined by the used soldering alloy and the physical properties and limitations of the materials to be soldered. Both soak profiles and ramp profiles are possible. Reflow profile suggestions below and on next page.

Reflow profile suggestions for Sn(Ag)Cu alloys







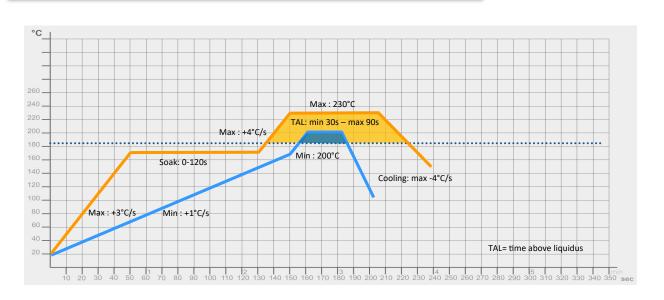
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Reflow profile suggestions for SnPb(Ag) alloys

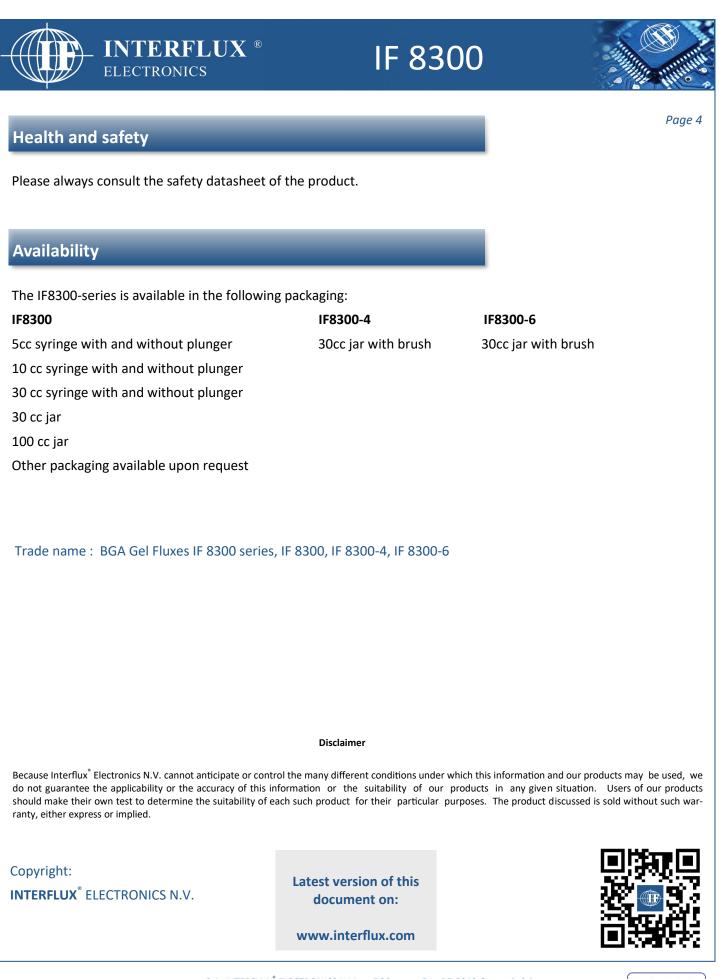


Test results

conform EN 61190-1-1(2002) and IPC J-STD-004A

Property	Result	Method
Chemical		
Flux designator	RE / L0	J-STD-004A
Qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32
Qualitative halide		
Silver chromate (Cl, Br)	pass	J-STD-004A IPC-TM-650 2.3.33
Environmental		
SIR test	pass	J-STD-004A IPC-TM-650 2.6.3.3
Qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15





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